

L Number	Hits	Search Text	DB	Time stamp
1	23	'Y' near wiring near lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:13
2	18	'X' near wiring near lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:13
4	9	('Y' near wiring near lines) and ('X' near wiring near lines)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:41
5	1	('X' near wiring near lines) and LCD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:41
6	1	('Y' near wiring near lines) and LCD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:42
8	3	('X' near wiring near lines) and board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:42
7	5	('Y' near wiring near lines) and board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:42
17	242	(257/266).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:31
18	6	((257/266).CCLS.) and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:32
19	350	(257/798).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:31
20	11	((257/798).CCLS.) and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
21	2	("6556264").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:54

22	0	(315/169a).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:55
23	0	(315/169).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:55
24	2784	(174/255,260).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:55
25	608	((174/255,260).CCLS.) and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
26	161	((((174/255,260).CCLS.) and multilayer) and electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
27	395	((((174/255,260).CCLS.) and multilayer) and (electrodes or wirings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
28	179	(((((174/255,260).CCLS.) and multilayer) and (electrodes or wirings)) and (insulat\$3 adj layer) and (substrate or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:57
29	179	(((((174/255,260).CCLS.) and multilayer) and (electrodes or wirings)) and (insulat\$3 adj layer) and (substrate or board)) and (substrate or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:57
-	1158	349/\$.ccls. and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:25
-	899	(349/\$.ccls. and multilayer) and electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
-	908	(349/\$.ccls. and multilayer) and (electrodes or wirings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:56
-	241	((349/\$.ccls. and multilayer) and (electrodes or wirings)) and (insulat\$3 adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:21

-	230	(((349/\$.ccls. and multilayer) and (electrodes or wirings)) and (insulat\$3 adj layer)) and (substrate or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:57
-	437	345/\$.ccls. and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:21
-	275	(345/\$.ccls. and multilayer) and electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:20
-	275	((345/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:20
-	85	(((345/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)) and (insulat\$3 adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:20
-	80	(((345/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)) and (insulat\$3 adj layer)) and (substrate or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:20
-	15070	257/\$.ccls. and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:24
-	7682	(257/\$.ccls. and multilayer) and electrodes	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:21
-	7682	((257/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:23
-	3097	(((257/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)) and (insulat\$3 adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:22
-	3030	(((257/\$.ccls. and multilayer) and electrodes) and (electrodes or wirings)) and (insulat\$3 adj layer)) and (substrate or board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:22
-	1848	(257/\$.ccls. and multilayer) and display	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:23

-	1543	((257/\$.ccls. and multilayer) and display) and (electrodes or wirings)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:23
-	62	((((257/\$.ccls. and multilayer) and display) and (electrodes or wirings)) and ('same' near plane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:27
-	3727	257/\$.ccls. and(LCD liquid near display)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:25
-	1197	(257/\$.ccls. and(LCD liquid near display)) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:26
-	1154	((257/\$.ccls. and(LCD liquid near display)) and wiring) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 10:27
-	74	((((257/\$.ccls. and(LCD liquid near display)) and wiring) and substrate) and ('same' near plane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 13:24
-	4	09/751614	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/31 12:12